



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



NOTES:

1) MATERIAL:

HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
 INSULATOR: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
 TERMINALS: PHOSPHOR BRONZE, .012/(0.30) THICK
 SHIELD: BRASS, .007/(0.18) THICK

2) FINISH:

TERMINALS:

- A = SELECT GOLD IN CONTACT AREA: 50 MICROINCHES / 1.27 MICROMETERS MIN.,
 *SELECT TIN IN PC TAIL AREA: 100 MICROINCHES / 2.54 MICROMETERS MIN.,
 WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES / 1.27 MICROMETERS MIN.
- B = SELECT GOLD IN CONTACT AREA: 30 MICROINCHES / 0.76 MICROMETERS MIN.,
 *SELECT TIN IN PC TAIL AREA: 100 MICROINCHES / 2.54 MICROMETERS MIN.,
 WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES / 1.27 MICROMETERS MIN.

SHIELD:

- *100 MICROINCHES / 2.54 MICROMETERS NICKEL OVER 50 MICROINCHES / 1.27 MICROMETERS COPPER UNDERPLATE; PCB GROUND TABS DIPPED IN TIN
- *THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD IN THE PC TAILS AND/OR SHIELD.

3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43249.

4) PACKAGING SPECIFICATION:

- UNSHIELDED CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS PER MOLEX PACKAGING SPECIFICATION PK-43249-004.
- UNSHIELDED CONNECTOR ASSEMBLIES PACKAGED IN TUBES PER MOLEX PACKAGING SPECIFICATION PK-43249-005.
- SHIELDED CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS PER MOLEX PACKAGING SPECIFICATION PK-44050-004.

5) MATES WITH: MODULAR PLUGS THAT CONFORM TO FCC REGULATION PART 68.5.

6) SEE SHEET 3 FOR SHIELDED JACK ASSEMBLY.

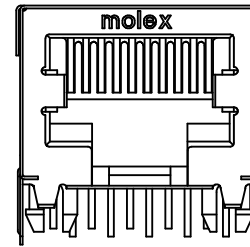
7) SEE SHEETS 5 & 6 FOR P.C. BOARD LAYOUTS.

8) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.

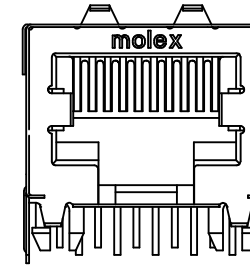
9) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

10) THIS PART CONFORMS TO FCC REGULATION 68.5 AND TIA 1096 FOR MODULAR JACKS.

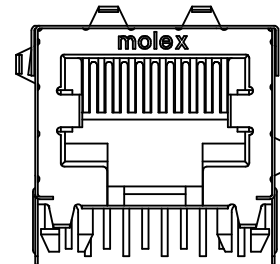
SIDE/TOP GROUND TAB OPTIONS FOR SHIELDS



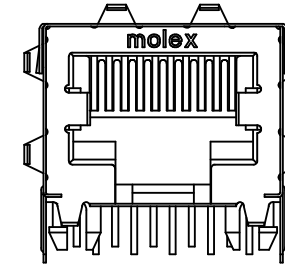
OPTION "A"
NO TOP OR SIDE TABS



OPTION "B"
TOP TABS

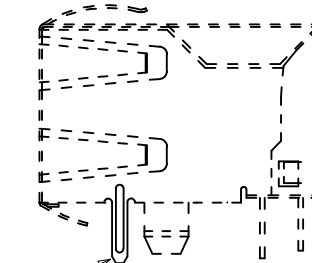


OPTION "C"
TOP AND STAGGERED SIDE TABS

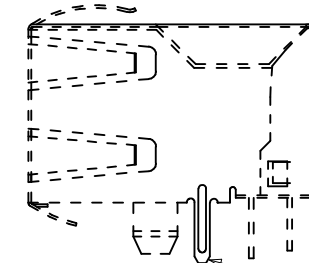


OPTION "D"
TOP AND SIDE TABS

BOTTOM PCB GROUND TAB OPTIONS FOR SHIELDS



OPTION "E"
OPTIONAL FRONT POSITION



OPTION "F"
OPTIONAL REAR POSITION

NOTE: EITHER PCB GROUND TAB OPTION IS AVAILABLE ON ALL SIDE/TOP TAB CONFIGURATIONS

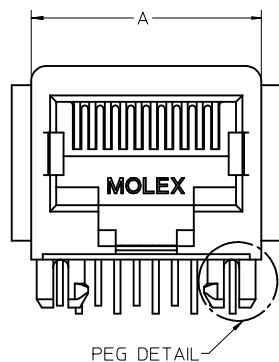
DRAWING LEGEND

- SHEET 1- NOTES, GROUND TAB OPTIONS
- SHEET 2- UNSHIELDED MODULAR JACK
- SHEET 3- SHIELDED MODULAR JACK WITH OPTIONAL SIDE/TOP GROUND TABS & BOTTOM GROUND TAB WITH OPTIONAL POSITION.
- SHEET 4- PART NUMBER CHARTS
- SHEET 5- FOOTPRINT LAYOUT FOR 8 POSITION HOUSING
- SHEET 6- FOOTPRINT LAYOUT FOR 6 POSITION HOUSING

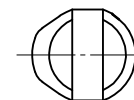
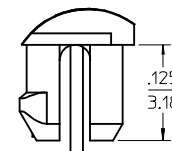
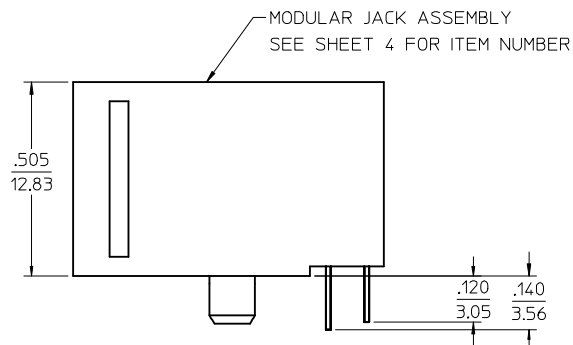
OBSOLETE PN EC NO: UCP2017-0615 DRW:WAFENG02 2016/09/20 CHKD: APPR:KLANG 2016/09/28 REV: K2	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>± .---</td> <td>± .---</td> </tr> <tr> <td>3 PLACES</td> <td>± .---</td> <td>± .010</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.25</td> <td>± .---</td> </tr> <tr> <td>1 PLACE</td> <td>± .---</td> <td>± .---</td> </tr> </tbody> </table> ANGULAR ±1/2°		mm	INCH	4 PLACES	± .---	± .---	3 PLACES	± .---	± .010	2 PLACES	± 0.25	± .---	1 PLACE	± .---	± .---	DIMENSION STYLE IN/MM DRAWN BY DATE JTR 1993/06/23 CHECKED BY DATE JTR 1993/06/23 APPROVED BY DATE RAS 1993/06/23	SCALE 4:1 DESIGN UNITS INCH THIRD ANGLE PROJECTION	TITLE LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY
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MATERIAL NO. SEE SHEET 4	MOLEX INCORPORATED	SHEET NO. 1 OF 6																		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MOLEX INCORPORATED	SHEET NO. 1 OF 6																		
SIZE THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	DOCUMENT NO. SDA-43249	SHEET NO. 1 OF 6																		

UNSHIELDED MODULAR JACK

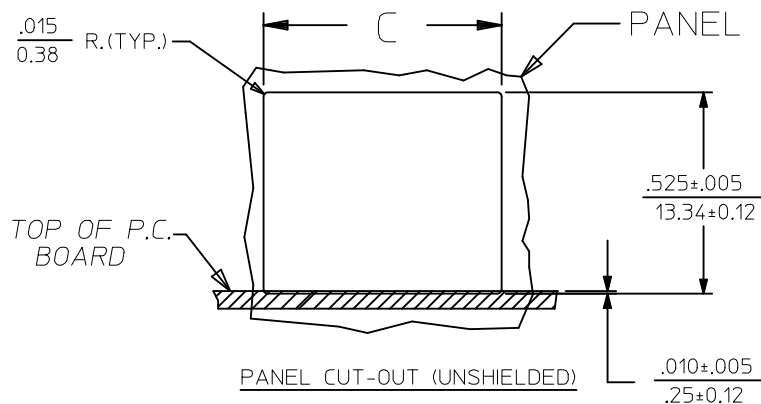
8 POSITION LOADED 10 SIZE SHOWN



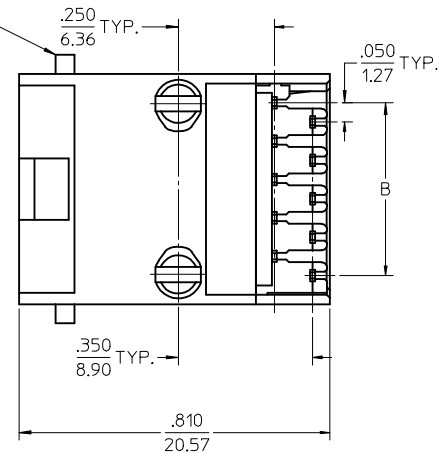
PEG DETAIL



PEG DETAIL
SCALE 8:1



OPTIONAL FLANGE
USED FOR FLUSH
MODULAR JACK

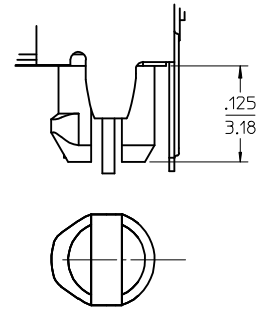
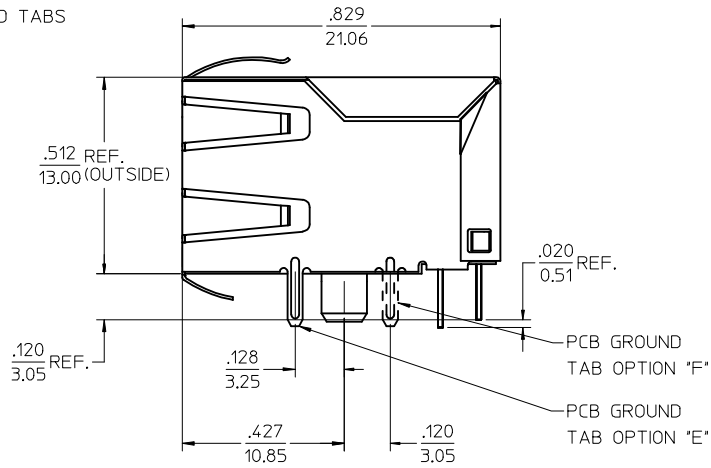
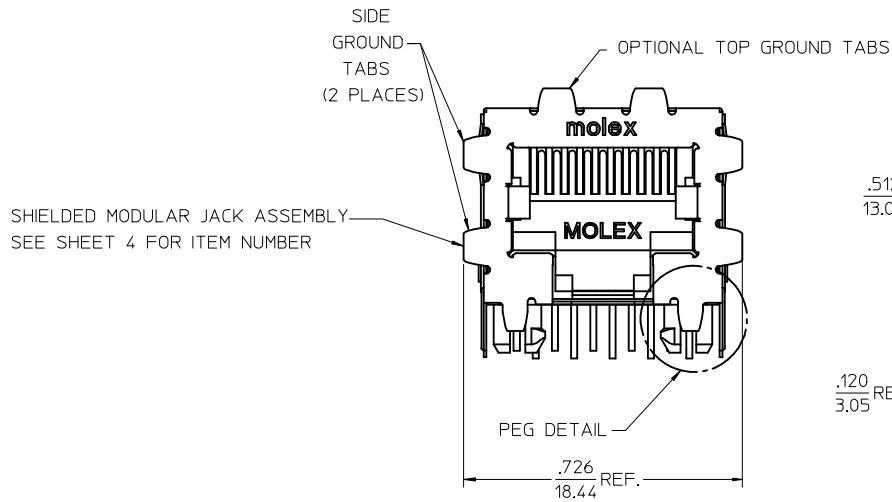


HOUSING SIZE	CIRCUIT SIZE	DIM. A	DIM. B	DIM. C
8	10	.600±.005 (15.24±0.13)	.450±.005 (11.43±0.13)	.620±.005 (15.75±0.13)
8	8	.600±.005 (15.24±0.13)	.350±.005 (8.89±0.13)	.620±.005 (15.75±0.13)
8	4	.600±.005 (15.24±0.13)	.150±.005 (3.81±0.13)	.620±.005 (15.75±0.13)
8	6	.600±.005 (15.24±0.13)	.250±.005 (6.35±0.13)	.620±.005 (15.75±0.13)
6	6	.520±.005 (13.21±0.13)	.250±.005 (6.35±0.13)	.540±.005 (13.72±0.13)
6	4	.520±.005 (13.21±0.13)	.150±.005 (3.81±0.13)	.540±.005 (13.72±0.13)
6	2	.520±.005 (13.21±0.13)	.050±.005 (1.27±0.13)	.540±.005 (13.72±0.13)

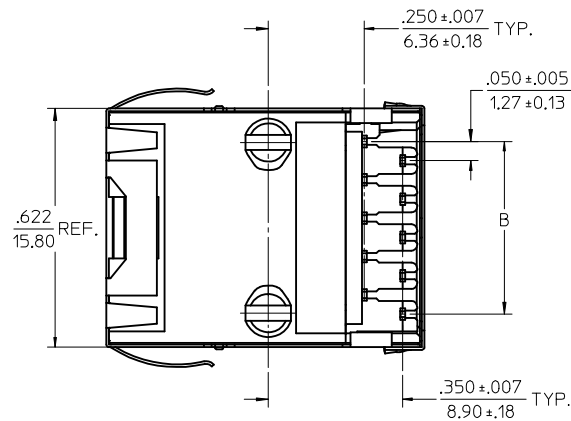
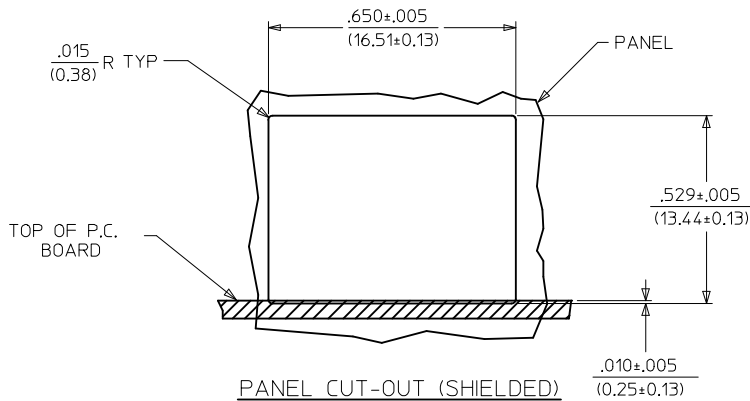
SEE SHEET 1 EC NO: UCP2017-06/15 DRW: WAFENG02 2016/09/20 CHKD: APPR: KLANG 2016/09/28 K2	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM	SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION
		4 PLACES ± --- ± --- 3 PLACES ± --- ± .010 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1/2°	mm INCH ± --- ± --- ± .010 ± --- ± --- ± --- ± --- ± ---	DRAWN BY DATE JTR 1993/06/23	CHECKED BY DATE JTR 1993/06/23	TITLE LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY DATE RAS 1993/06/23	MOLEX INCORPORATED		
		SEE SHEET 4		MATERIAL NO. SDA-43249	DOCUMENT NO.	SHEET NO. 2 OF 6	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

MODULAR JACK W/ .007" THICK SHIELD AND OPTIONAL GROUND TABS

8 LOADED 10 VERSION SHOWN WITH GROUND TAB OPTIONS "D" AND "E"



PEG DETAIL
SCALE 8:1



DESCRIPTION OF GROUND TAB OPTIONS:
(SEE SHEET 4 FOR AVAILABLE COMBINATIONS OF OPTIONS)

GROUND TAB OPTION	DESCRIPTION
A	NO GROUND TABS
B	TOP TABS ONLY
C	STAGGERED SIDE TABS
D	TOP AND SIDE TABS
E	PCB GROUND TAB IN FRONT POSITION
F	PCB GROUND TAB IN REAR POSITION

HOUSING SIZE	CIRCUIT SIZE	B
8	10	.450 ± .005 11.43 ± 0.13
8	8	.350 ± .005 8.89 ± 0.13

SEE SHEET 1 EC NO: UCP2017-0615 DRWNAFENG02 2016/09/20 CHKD: APPR: KLANG 2016/09/28 K2	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES ±</td> <td>---</td> <td>---</td> </tr> <tr> <td>3 PLACES ±</td> <td>---</td> <td>±.010</td> </tr> <tr> <td>2 PLACES ±</td> <td>0.25</td> <td>---</td> </tr> <tr> <td>1 PLACE ±</td> <td>---</td> <td>---</td> </tr> </tbody> </table> ANGULAR ±1/2°		mm	INCH	4 PLACES ±	---	---	3 PLACES ±	---	±.010	2 PLACES ±	0.25	---	1 PLACE ±	---	---	DIMENSION STYLE IN/MM	SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION
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1 PLACE ±	---	---																			
DRAWN BY JTR	DATE 1993/06/23	TITLE LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY																			
CHECKED BY JTR	DATE 1993/06/23	APPROVED BY RAS																			
DATE 1993/06/23	MATERIAL NO. SEE SHEET 4	DOCUMENT NO. SDA-43249	SHEET NO. 3 OF 6																		





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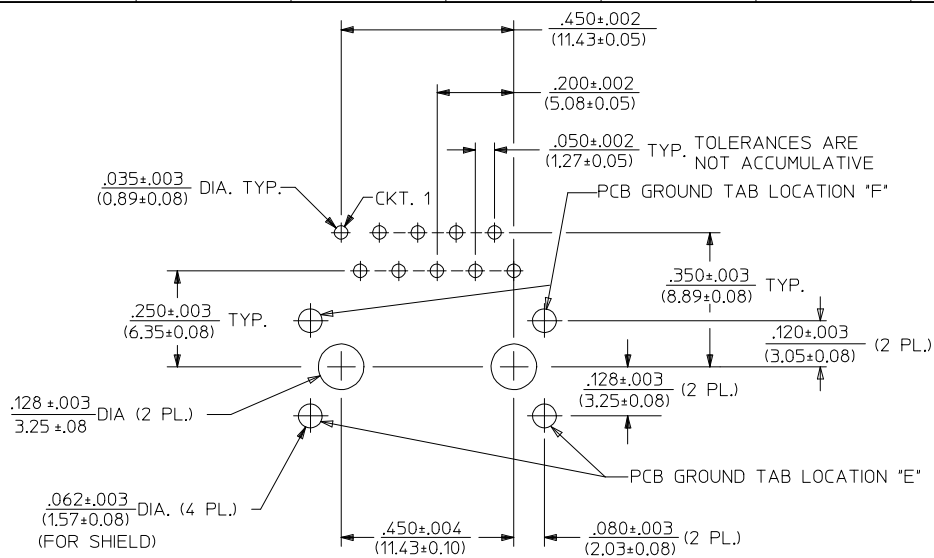
FLUSH MOUNT (UNSHIELDED)				
X=NOT TOOLED	ASSEMBLY ITEM NUMBER	CONNECTOR SIZE	NUMBER OF CIRCUITS	TERMINAL PLATING OPTION
X	43249-8001	8	10	A
	43249-8004	8	8	A
X	43249-8010	8	6	A
	43249-6001	6	6	A
X	43249-6004	6	4	A
X	43249-6007	6	2	A

FLANGELESS (UNSHIELDED)				
X=NOT TOOLED	ASSEMBLY ITEM NUMBER	CONNECTOR SIZE	NUMBER OF CIRCUITS	TERMINAL PLATING OPTION
X	43249-8101	8	10	A
X	43249-8102	8	10	B
	43249-8104	8	8	A
X	43249-8105	8	8	B
X	43249-8116	8	6	A
X	43249-8119	8	4	A
	43249-6101	6	6	A
	43249-6104	6	4	A
X	43249-6107	6	2	A

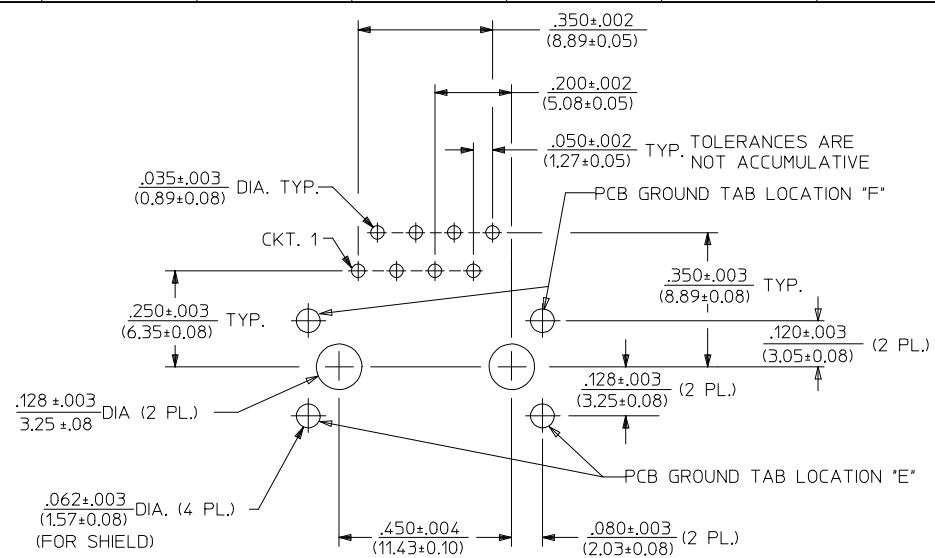
FLANGELESS (UNSHIELDED)				
(SHIPPED IN TUBES)				
X=NOT TOOLED	ASSEMBLY ITEM NUMBER	CONNECTOR SIZE	NUMBER OF CIRCUITS	TERMINAL PLATING OPTION
X	43249-6501	6	6	A
X	43249-6504	6	4	A

SHIELDED, .007" THICK							
X=NOT TOOLED	ASSEMBLY ITEM NUMBER	CONN. SIZE	NUMBER OF CIRCUITS	TERMINAL PLATING OPTION	SIDE/TOP PANEL GROUND TAB OPTION	PCB GROUND TAB OPTION	PACKAGING OPTION
	43249-8900	8	10	A	A	E	TRAY
X	43249-8901	8	10	A	B	E	TRAY
X	43249-8902	8	10	A	C	E	TRAY
X	43249-8903	8	10	A	D	E	TRAY
	43249-8908	8	10	A	A	F	TRAY
	43249-8909	8	10	A	B	F	TRAY
X	43249-8910	8	10	A	C	F	TRAY
	43249-8911	8	10	A	D	F	TRAY
	43249-8916	8	8	A	A	E	TRAY
	43249-8917	8	8	A	B	E	TRAY
X	43249-8918	8	8	A	C	E	TRAY
	43249-8919	8	8	A	D	E	TRAY
X	43249-8920	8	8	B	A	E	TRAY
	43249-8924	8	8	A	A	F	TRAY
X	43249-8925	8	8	A	B	F	TRAY
X	43249-8926	8	8	A	C	F	TRAY
	43249-8927	8	8	A	D	F	TRAY

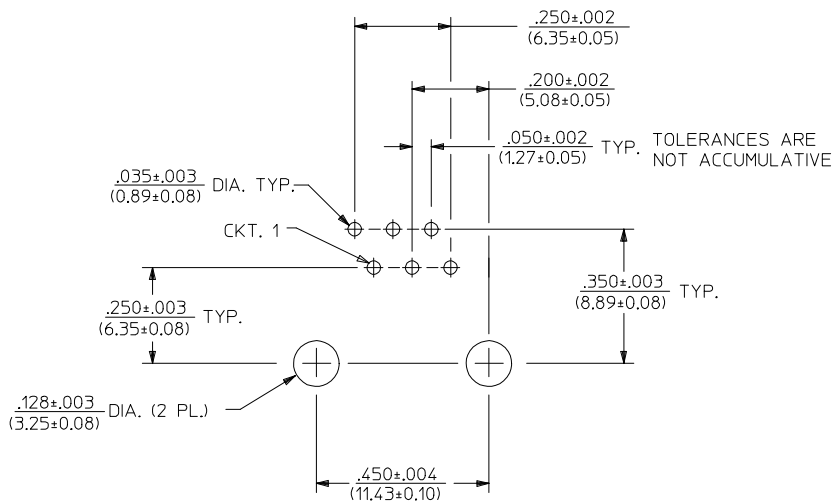
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MATERIAL NO. SEE CHART	DOCUMENT NO. SDA-43249	SHEET NO. 4 OF 6																		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																	
SIZE 																				



PC BOARD LAYOUT FOR SIZE 8, 10 CIRCUIT
(COMPONENT SIDE OF BOARD)



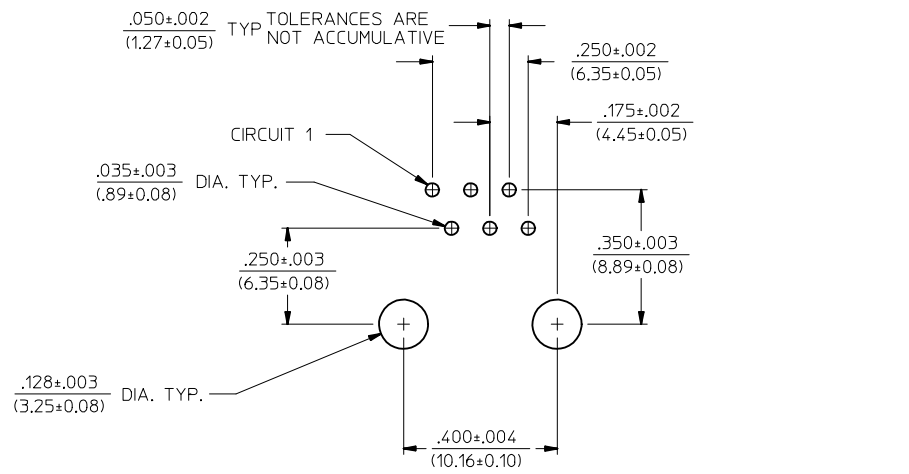
PC BOARD LAYOUT FOR SIZE 8, 8 CIRCUIT
(COMPONENT SIDE OF BOARD)



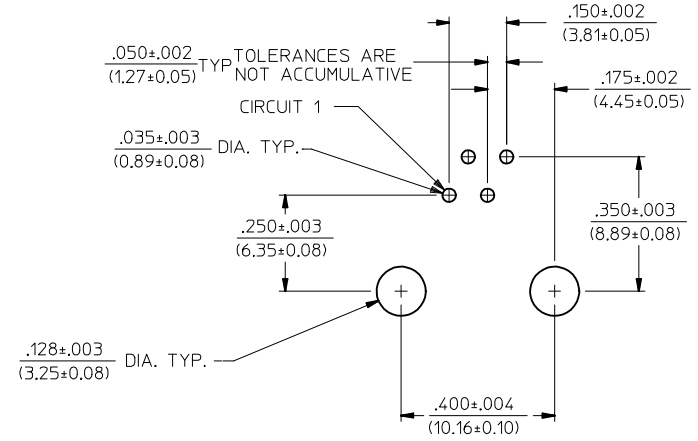
PC BOARD LAYOUT FOR SIZE 8, 6 CIRCUIT
(COMPONENT SIDE OF BOARD)

NOTES:
1. RECOMMENDED PCB THICKNESS: .062 ± .005 / (1.57 ± 0.13)

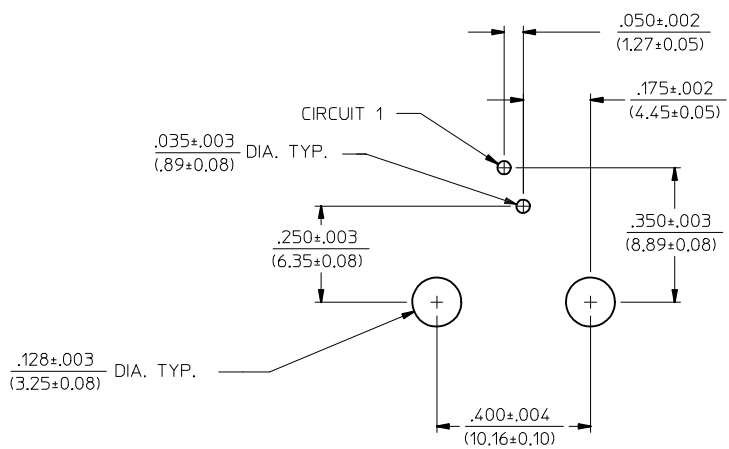
SEE SHEET 1 IEC NO: UCP2017-06/15 DRW: WAFENG02 2016/09/20 CHKD: APPR: KLANG 2016/09/28	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION	
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DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 4		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



PC BOARD LAYOUT FOR SIZE 6, 6 CIRCUIT
(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR SIZE 6, 4 CIRCUIT
(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR SIZE 6, 2 CIRCUIT
(COMPONENT SIDE OF BOARD)

NOTES:
1. RECOMMENDED PCB THICKNESS: .062±.005/(1.57±0.13)

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2 PLACES	± 0.25	± .---																		
1 PLACE	± .---	± .---																		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE SHEET 4 SIZE THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	MOLEX MOLEX INCORPORATED DOCUMENT NO. SDA-43249	SHEET NO. 6 OF 6																	